

In the Specification

At page 1, after the title insert:

CROSS REFERENCE TO RELATED APPLICATION

This is a Division of U.S. Patent Application Serial No. 09/148,723, filed September 3, 1998, entitled "Methods of Bonding Solder Balls to Bond Pads on a Substrate".

In the Claims

Cancel claims 1-3.

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4. (Amended) The method of bonding solder balls of claim 12, wherein said placing comprises placing individual solder balls within individual holes within the frame.

✓ 5. (Amended) The method of bonding solder balls of claim 12, wherein said placing comprises placing majority portions of individual solder balls within individual holes within the frame.

✓ 6. (Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads.